

FIG. 1

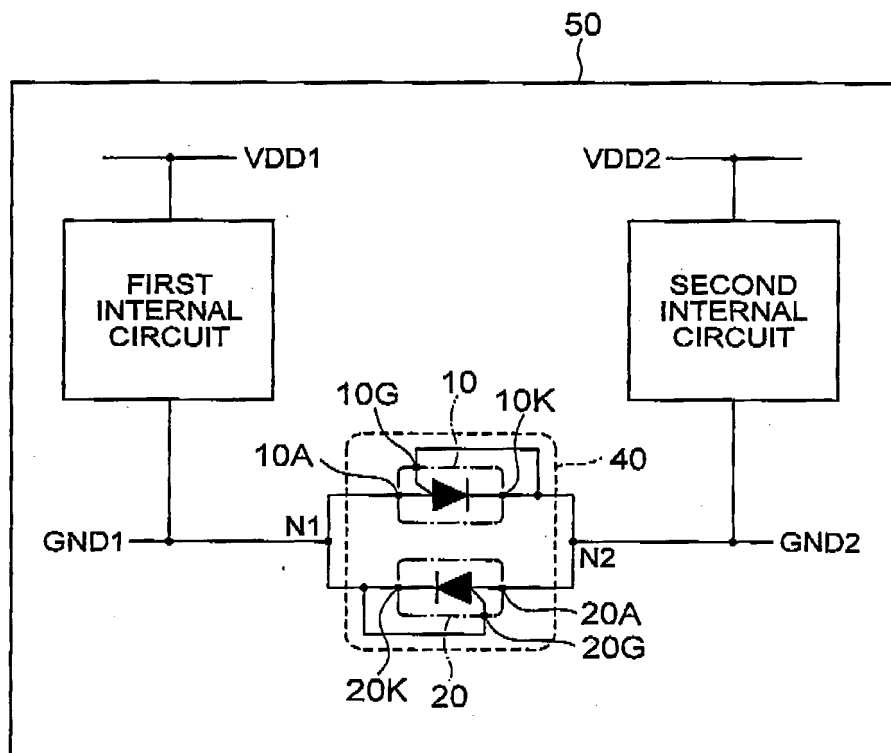


FIG. 2

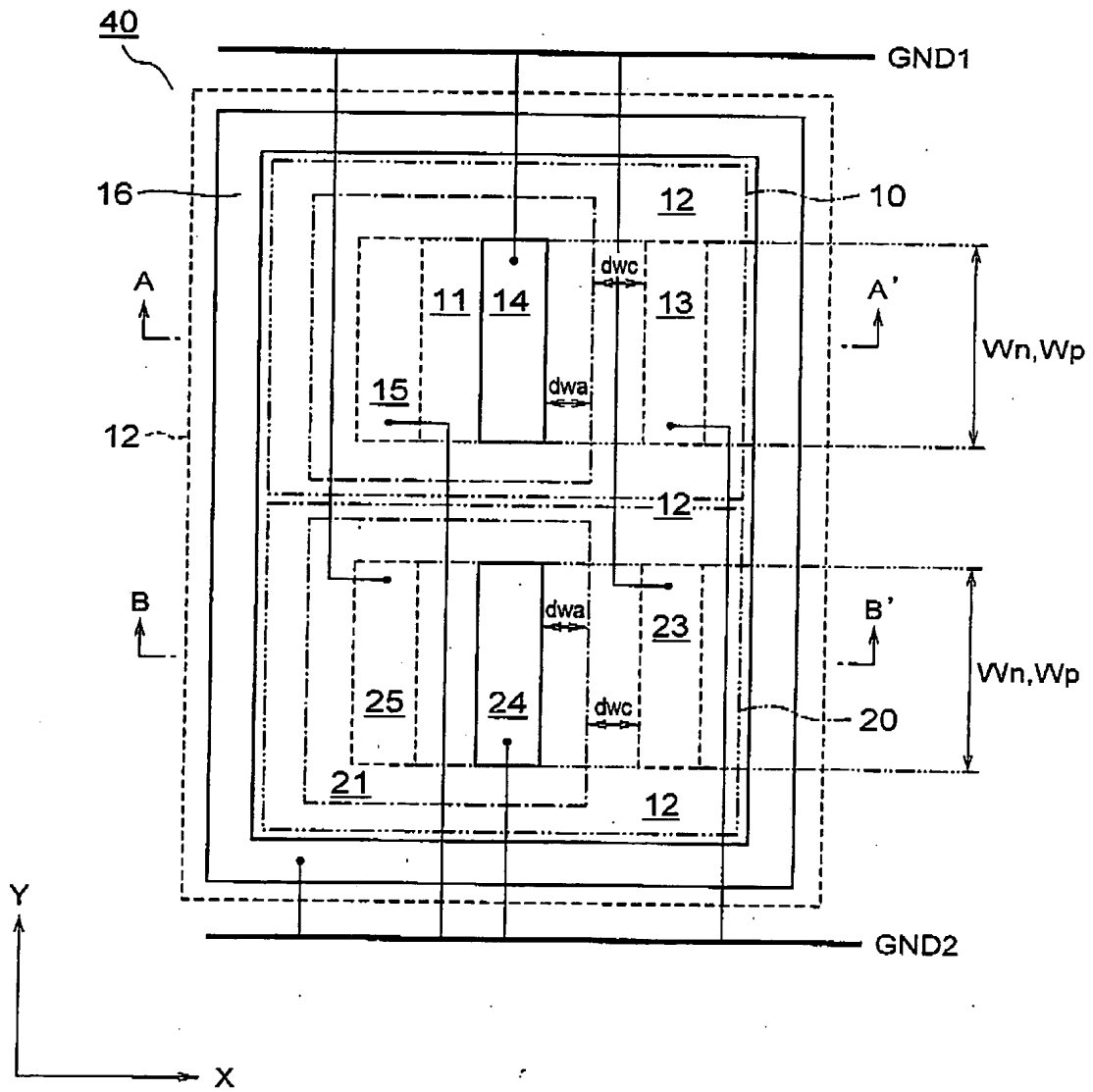


FIG. 3A

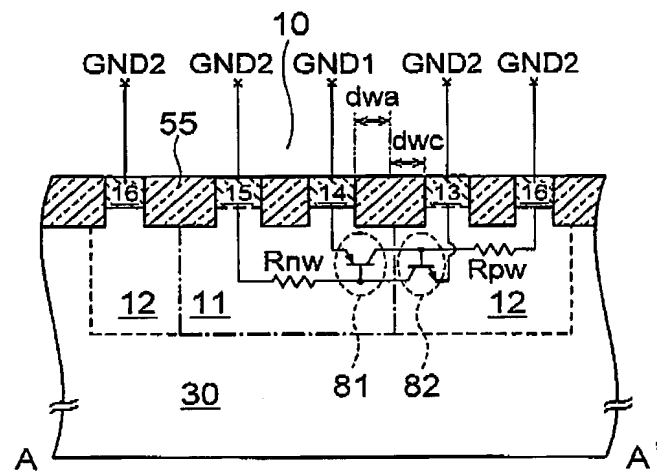


FIG. 3B

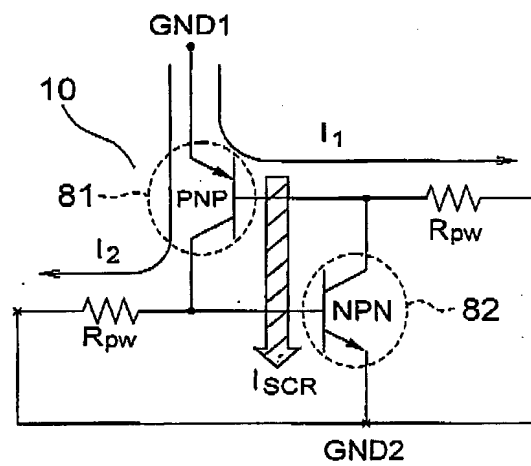


FIG. 4A

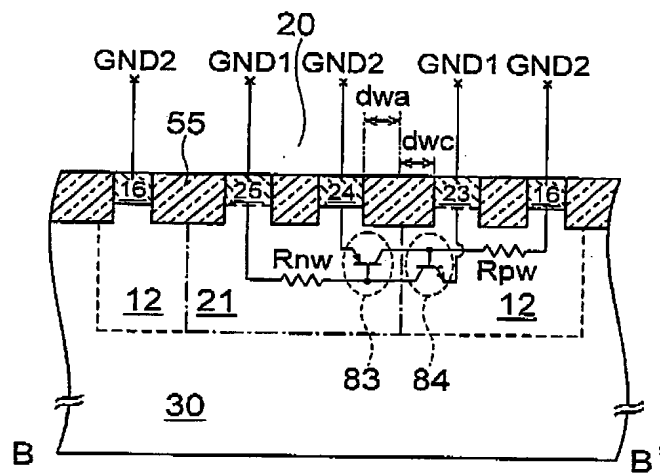


FIG. 4B

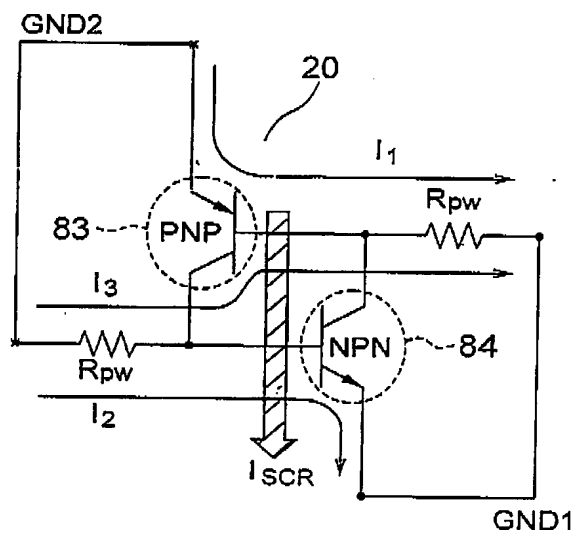


FIG. 5A

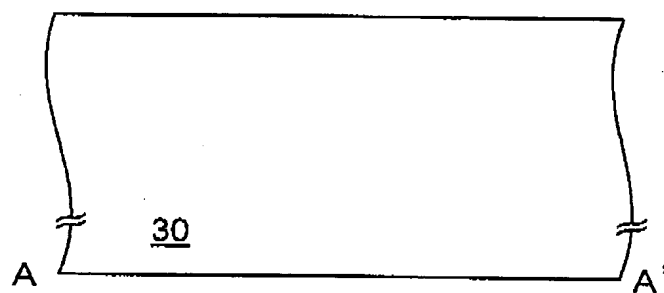


FIG. 5B

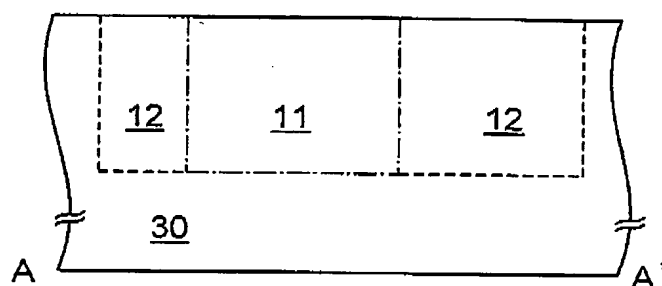


FIG. 5C

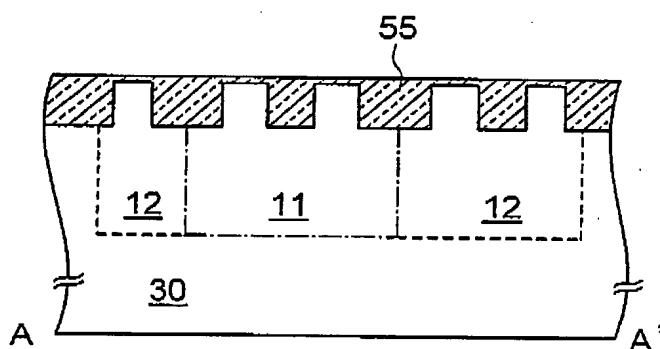


FIG. 5D

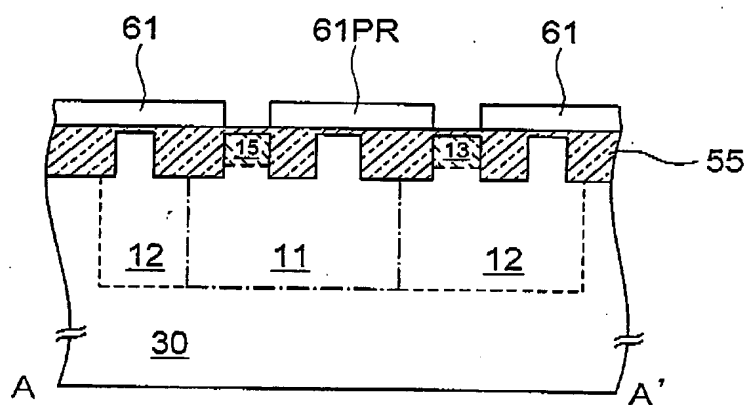


FIG. 5E

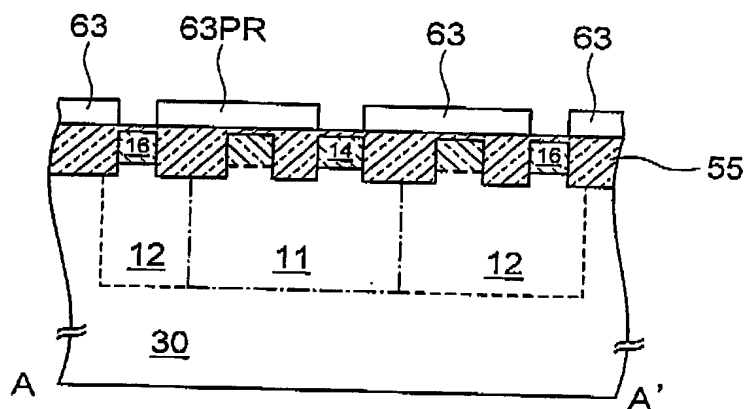


FIG. 5F

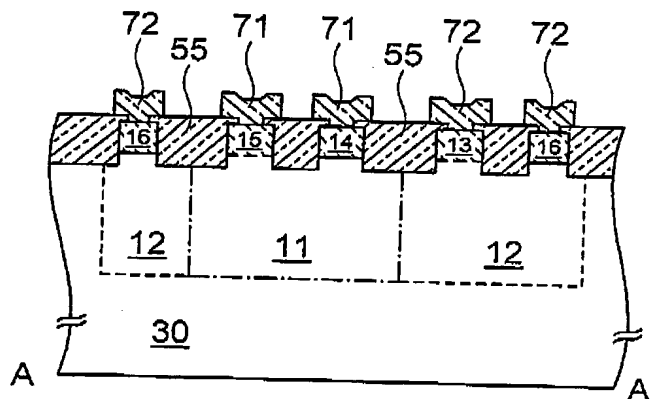


FIG. 6A

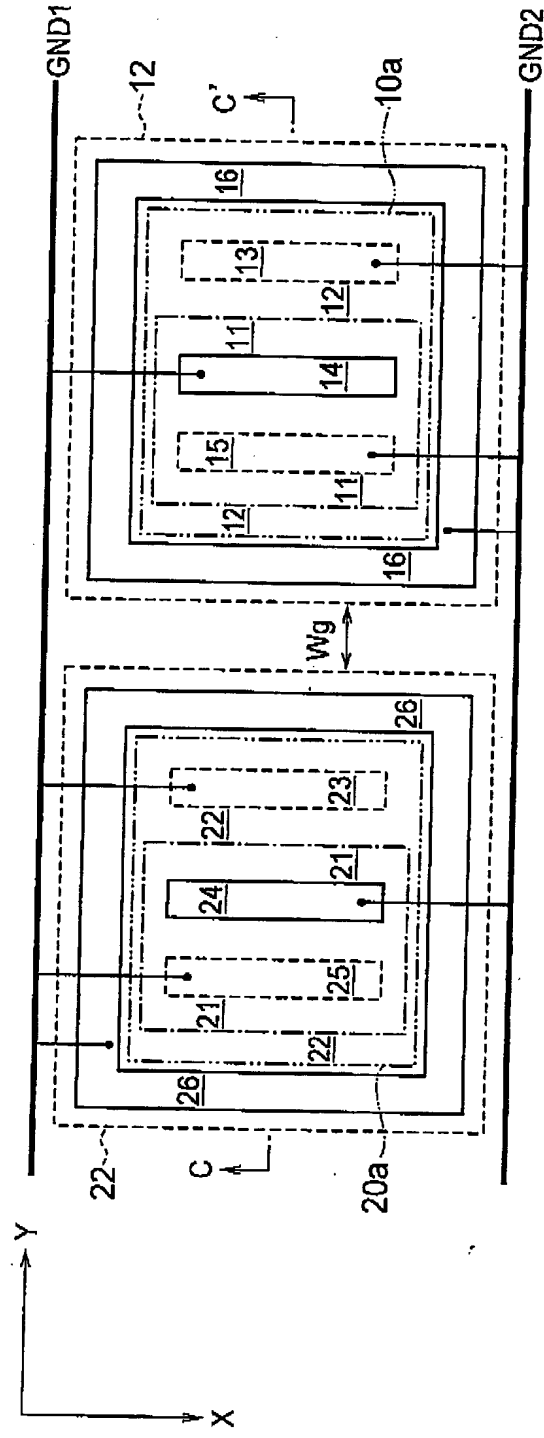
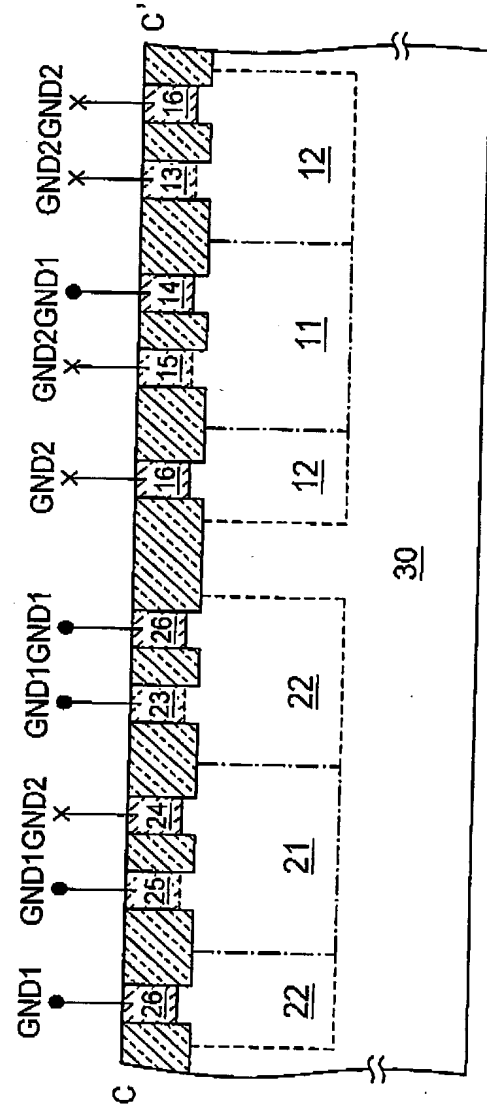


FIG. 6B



This cross-sectional view shows a substrate 30 with a multi-layered structure. The structure consists of alternating layers of conductive material (hatched) and insulating material (dotted). The layers are labeled 16, 23, 24, 25, 55, and 16 from top to bottom. The top layer 16 is connected to GND2, GND1, GND2, GND1, and GND2 respectively. The middle layer 23 is connected to GND1. The bottom layer 24 is connected to GND2. The top layer 25 is connected to GND1. The middle layer 55 is connected to GND2. The bottom layer 16 is connected to GND2. The structure is divided into three regions labeled 12, 21, and 12 from left to right.

FIG. 8A

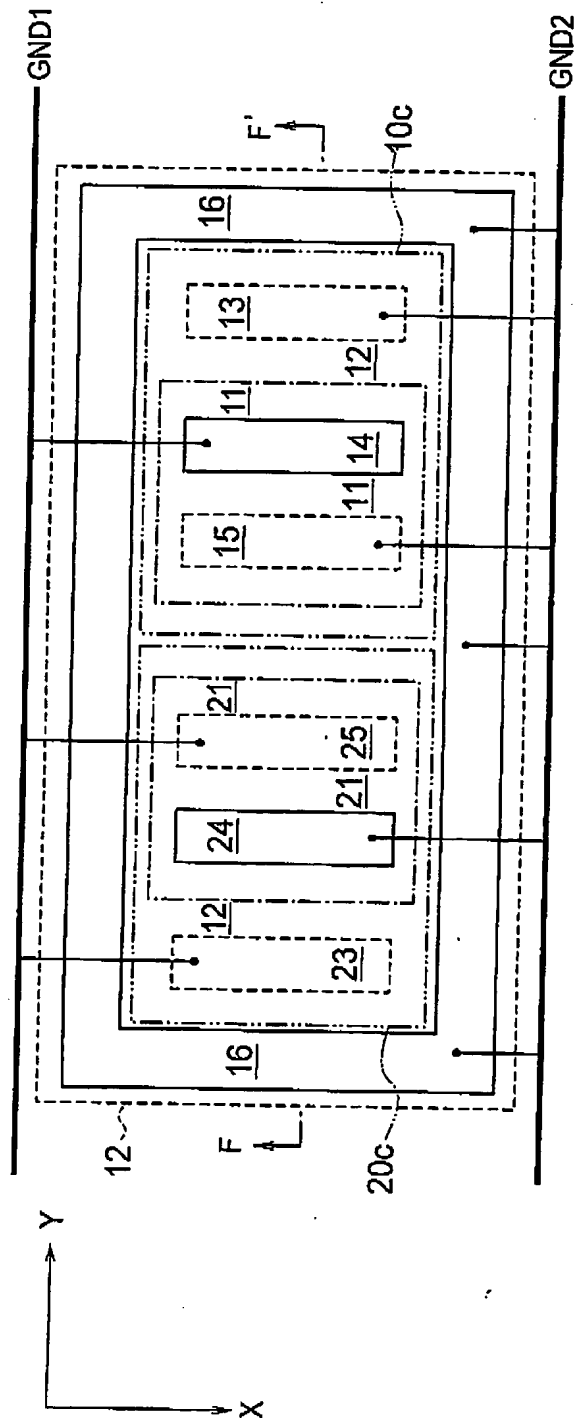


FIG. 8B

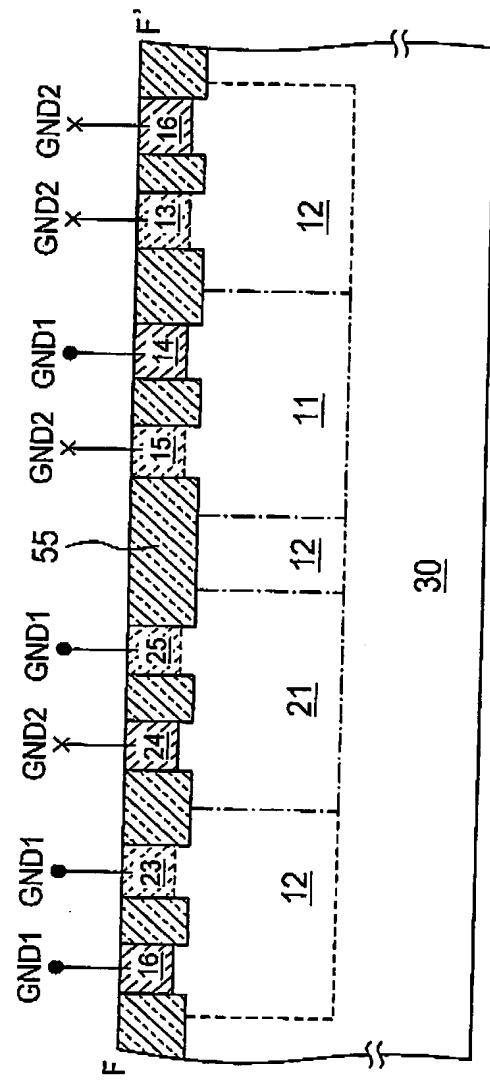


FIG. 9A

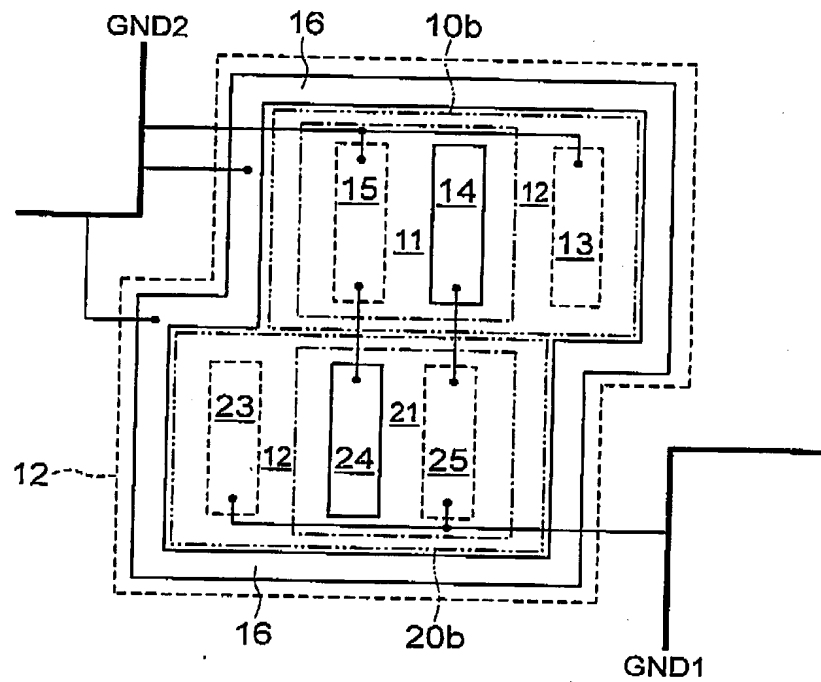


FIG. 9B

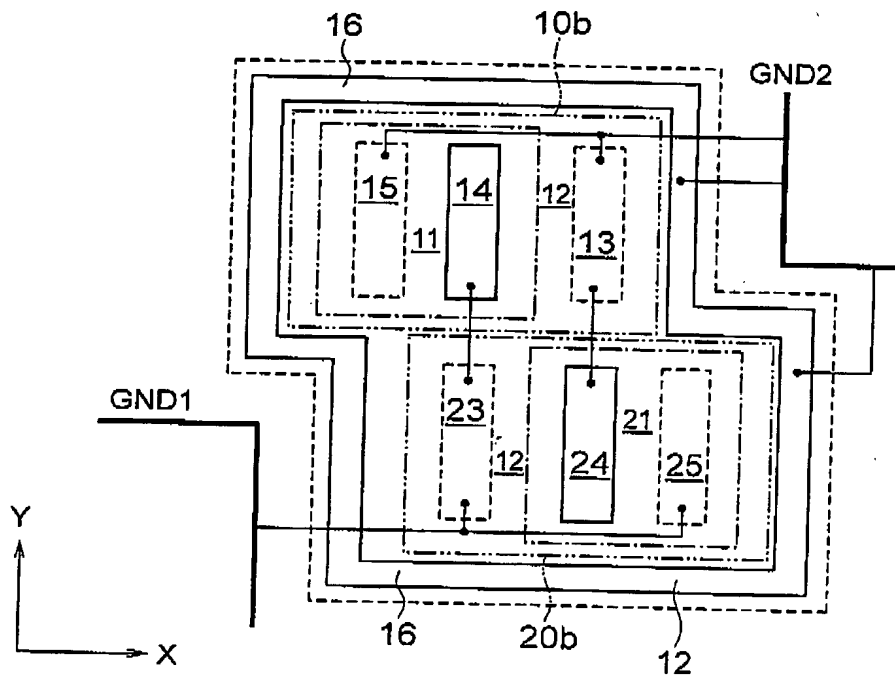


FIG. 10
PRIOR ART

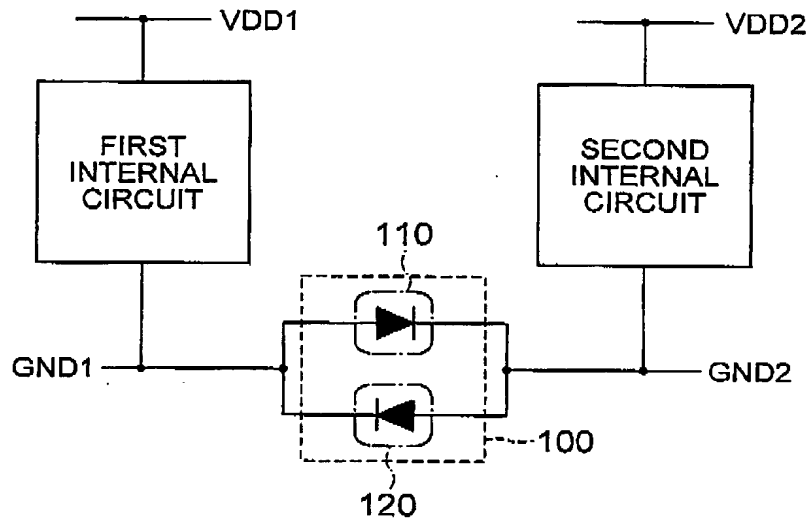


FIG. 11

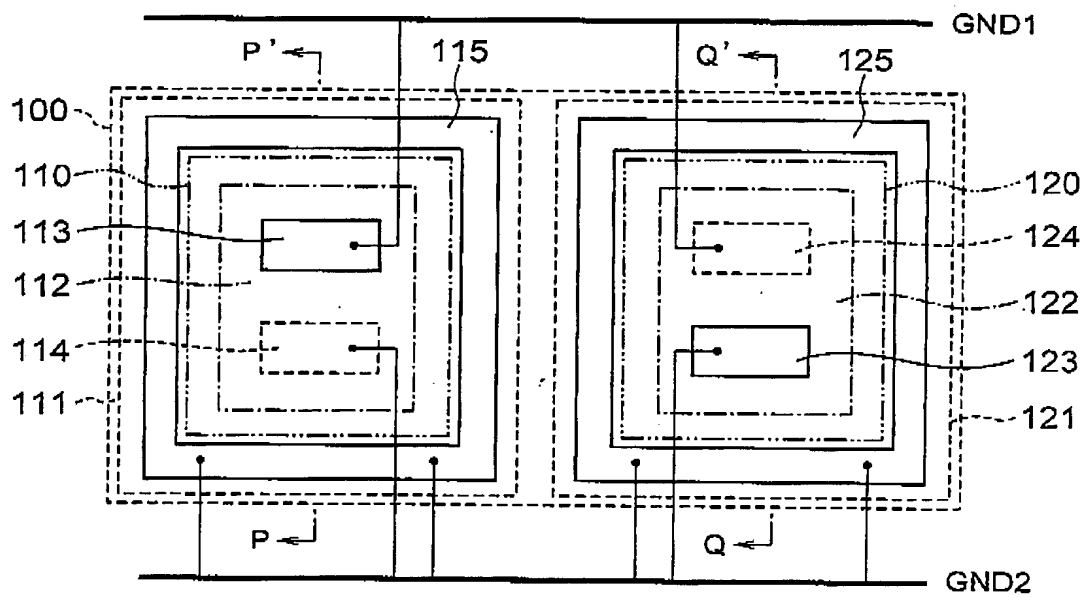


FIG.12A

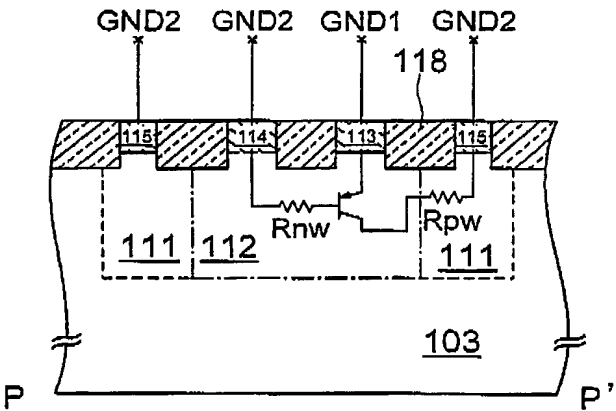


FIG.12B

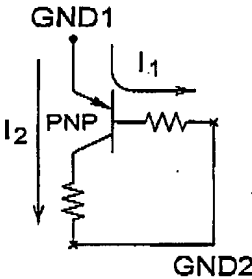


FIG.13A

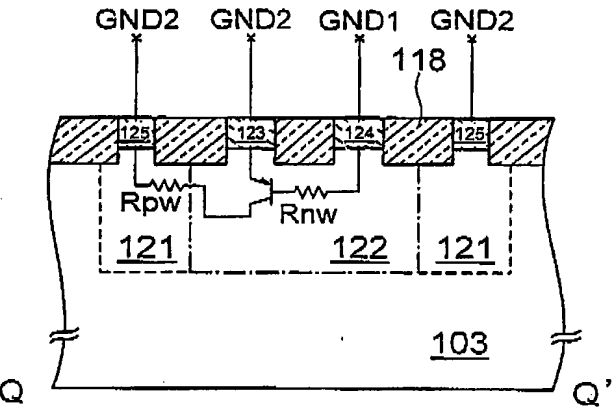


FIG.13B

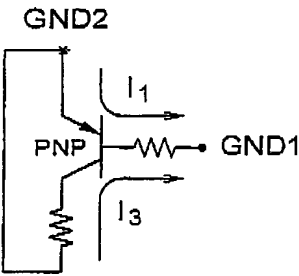


FIG. 14A

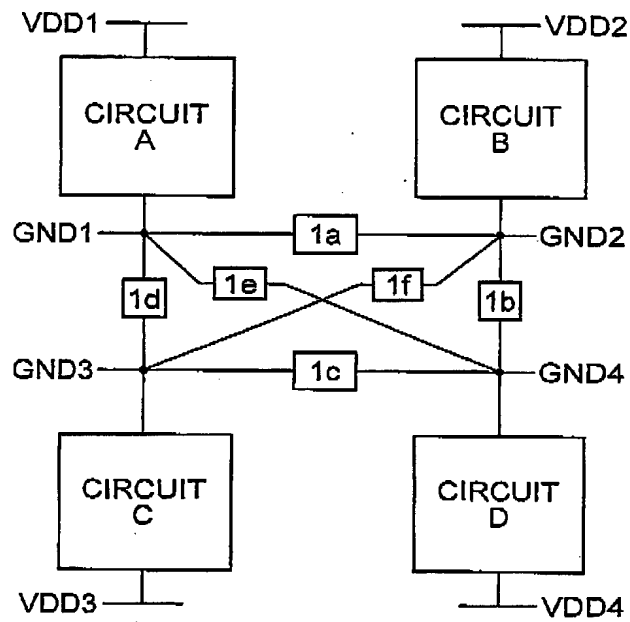


FIG. 14B

